

# Panel Fan-Out Manufacturing

## *Why, When, and How?*



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# Environment

- We all can agree that ....
  - Packaging is driving increased system performance and value.
  - Fan-out is blurring of the lines between silicon and package.
  - Question for tonight... WILL IT STOP AT WAFER LEVEL?
- Why will Panel disrupt the electronics Industry?
  - Cost, new functionality, or reliability
- When will this disruption occur?
  - Now, 2 to 5 years, or never
- How will this disruption materialize?
  - Scaling up from wafer level process or new technology

# Session Set Up

## Wafer Level Fan-Out



TSMC (Doug)



NANIUM (Steffen)

## Panel Level Fan-Out



IZM (Rolf)



DECA (Tim)

## Jury



Qualcomm (Steve)



Audience (YOU)